

ABSTRACT

A method of forming a hermetically sealed MEMS package includes a step of providing a supporting GaAs substrate with at least one contact for the MEMS device on the surface of the supporting substrate and forming a cantilever on the surface of the supporting substrate positioned to come into electrical engagement with the contact in one orientation. A metal seal ring is fixed to the surface of the supporting substrate circumferentially around the contact and the cantilever. A cavity is etched in a silicon chip to form a cap member. A metal seal ring is fixed to the cap member around the cavity. The package is hermetically sealed by reflowing a solder alloy, positioned between the two seal rings, in an inert environment without the use of flux.